

DATA ITEM DESCRIPTION			Form Approved OMB No. 0704-0188	
2 TITLE INTEGRATED CIRCUIT GRAPHICS DATA BASE		1 IDENTIFICATION NUMBER DI-IPSC-80409		
3. DESCRIPTION / PURPOSE 3.1 This data base documents all geometric and associated layout information used in the generation of integrated circuits.				
4 APPROVAL DATE (YYMMDD) 870810	5. OFFICE OF PRIMARY RESPONSIBILITY (OPR) G/Y223	6a DTIC APPLICABLE	6b GIDEP APPLICABLE	
7 APPLICATION / INTERRELATIONSHIP 7.1 This data item description (DID) contains the format and content preparation instructions for the integrated circuit graphics data base generated by the specific and discrete task requirement as delineated in the contract. 7.2 Normally used when custom integrated circuits are being developed in conjunction with other integrated circuit data items.				
8 APPROVAL LIMITATION		9a APPLICABLE FORMS	9b AMSC NUMBER G4178	
10. PREPARATION INSTRUCTIONS 10.1 <u>Data base tape format:</u> Format and recording shall be compatible with those employed by CALMA in CALMA GDS II systems. Tapes created must be 9 track and either 800 BPI or 1600 BPI. 10.2 <u>Data base format:</u> a. CALMA GDS II tapes shall be in accordance with the CALMA GDS II Stream format (OUTFORM). b. Information contained in the library shall be complete. Any graphic cell (or structure) used in describing the integrated circuit or any other graphic cell (including test) shall be included in the library. 10.3 <u>Documentation.</u> 10.3.1 The following information shall be provided on 8-1/2 x 11 inch (Metric size A4) paper: a. Title. Chip name/project name. b. Company/division. c. Contract number. d. Revision date of chip and/or cells (as appropriate). e. Circuit description. f. Tape format (GDS II stream format). g. Name(s) of library or libraries on tape(s). (Continued on Page 2)				
11 DISTRIBUTION STATEMENT <u>DISTRIBUTION STATEMENT A:</u> Approved for public release; distribution is unlimited.				

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Block 10, Preparation Instructions (Continued)

- h. Name of graphic cell or structure containing the chip description.
- i. Cross reference of graphic layers as they correspond to fabrication.
- j. Listing of the line code table used to resolve polygons (if appropriate).
- k. Data scale in design units (i.e., Mils, Microns, etc.) per GDS.
- l. Tape density.
- m. Date on which the tape was created.
- n. Revision date of chip and/or cells (as appropriate).
- o. Chip ON number.
- p. Classification.
- q. Number of files.
- r. Contract number.

10.3.2 A peel-off label shall be affixed to each tape with the following information:

- a. Chip name/project name.
- b. Date on which the tape was created.
- c. Tape format GDS II stream format
- d. Tape density.
- e. Name(s) of library of libraries on tape.
- f. Classification.